

HfO₂ based RRAM : Insight from experiment and ab-initio calculations

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In recent years, considerable research effort have been devoted to the development and understanding of resistive random access memories (*RRAM*) due to, among others, their low power operation, ease of integration and compatibility with *CMOS* [1-2]. The working principle of these *RRAMs* relies on the reversible breakdown of the oxide layer (in this case *HfO_x*) that leads to a deep resistance change. By alternating the voltage polarity (for bipolar devices) at proper levels or using the same polarity at different voltage levels (for unipolar devices), the resistance of the oxide layer can be changed from low resistance state (*LRS*) to high resistance state (*HRS*) or vice versa. *LRS* is attributed to the creation/reconstruction of a conductive path called conductive filament (*CF*) while *HRS* is associated with the rupture of the *CF*. An initial forming step that leads to *CF* creation is required in these *RRAM* devices. This forming operation generally involves high voltages and places considerable electrical stress on the memory cells affecting their expected behavior.

For the purpose of investigating the forming operation, the methodology to reduce and/or eliminate this step, and assessing the choice of electrode material on *RRAM* performance, different types of samples were processed and characterized. Furthermore, we used ab-initio calculations to gain more insight on both the effects of electrode material choice on the forming step of *RRAM* devices and the possible atomistic structure of samples not requiring forming.

Références

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